SN65LVDS179-Q1, SN65LVDS180-Q1, SN65LVDS050-Q1, SN65LVDS051-Q1 HIGH-SPEED DIFFERENTIAL LINE DRIVERS AND RECEIVERS

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- Qualification in Accordance With AEC-Q100†
- Qualified for Automotive Applications
- Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Meets or Exceeds the Requirements of ANSI TIA/EIA-644-1995 Standard
- Signaling Rates up to 400 Mbps
- Bus-Terminal ESD Exceeds 12 kV
- Operates From a Single 3.3-V Supply
- Low-Voltage Differential Signaling With Typical Output Voltages of 350 mV and a 100-Ω Load
- Propagation Delay Times

Driver: 1.7 ns TypReceiver: 3.7 ns Typ

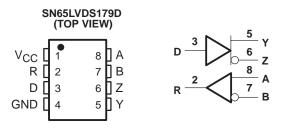
Power Dissipation at 200 MHz

Driver: 25 mW TypicalReceiver: 60 mW Typical

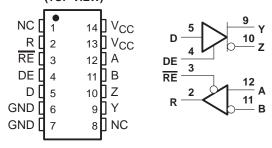
- LVTTL Input Levels Are 5-V Tolerant
- Receiver Maintains High Input Impedance With V_{CC} < 1.5 V
- Receiver Has Open-Circuit Fail Safe

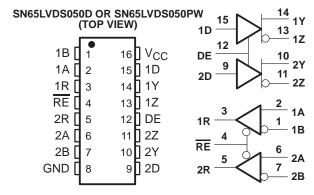
description/ordering information

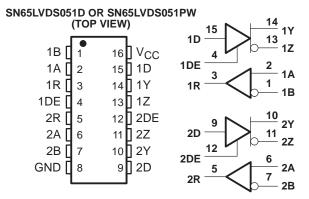
The SN65LVDS179, SN65LVDS180, SN65LVDS050, and SN65LVDS051 are differential line drivers and receivers that use low-voltage differential signaling (LVDS) to achieve signaling rates as high as 400 Mbps. The TIA/EIA-644 standard compliant electrical interface provides a minimum differential output voltage magnitude of 247 mV into a $100-\Omega$ load and receipt of 50-mV signals with up to 1 V of ground potential difference between a transmitter and receiver.



SN65LVDS180D OR SN65LVDS180PW (TOP VIEW)









Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



[†] Contact factory for details. Q100 qualification data available on request.

SN65LVDS179-Q1, SN65LVDS180-Q1, SN65LVDS050-Q1, SN65LVDS051-Q1 HIGH-SPEED DIFFERENTIAL LINE DRIVERS AND RECEIVERS

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description/ordering information (continued)

The intended application of this device and signaling technique is for point-to-point baseband data transmission over controlled impedance media of approximately $100-\Omega$ characteristic impedance. The transmission media may be printed-circuit board traces, backplanes, or cables. (Note: The ultimate rate and distance of data transfer is dependent upon the attenuation characteristics of the media, the noise coupling to the environment, and other application specific characteristics).

The devices offer various driver, receiver, and enabling combinations in industry standard footprints. Since these devices are intended for use in simplex or distributed simplex bus structures, the driver enable function does not put the differential outputs into a high-impedance state but rather disconnects the input and reduces the quiescent power used by the device. (For these functions with a high-impedance driver output, see the SN65LVDM series of devices.) All devices are characterized for operation from -40° C to 85° C.

ORDERING INFORMATION

TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
4000 1- 0500	SOIC (D)	Tape and Reel	SN65LVDS179DRQ1‡	VDS179Q
-40°C to 85°C	TSSOP (PW)	Tape and Reel	SN65LVDS179PWRQ1‡	VDS179Q
4000 1- 0500	SOIC (D)	Tape and Reel	SN65LVDS180DRQ1	VDS180Q
-40°C to 85°C	TSSOP (PW)	Tape and Reel	SN65LVDS180PWRQ1	VDS180Q
4000 / 0500	SOIC (D)	Tape and Reel	SN65LVDS050DRQ1‡	VDS050Q
-40°C to 85°C	TSSOP (PW)	Tape and Reel	SN65LVDS050PWRQ1‡	VDS050Q
4000 / 0500	SOIC (D)	Tape and Reel	SN65LVDS051DRQ1	VDS051Q
-40°C to 85°C	TSSOP (PW)	Tape and Reel	SN65LVDS051PWRQ1	VDS051Q

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



[‡] Product Preview

Function Tables

SN65LVDS179 RECEIVER

INPUTS	OUTPUT
$V_{ID} = V_A - V_B$	R
$V_{ID} \ge 50 \text{ mV}$	Н
$-50 \text{ mV} < V_{\text{ID}} < 50 \text{ mV}$?
V _{ID} ≤ −50 mV	L
Open	Н

H = high level, L = low level, ? = indeterminate

SN65LVDS179 DRIVER

INPUT	OUTPUTS				
D	Y Z				
L	L	Н			
Н	Н	L			
Open	L	Н			

H = high level, L = low level

SN65LVDS180, SN65LVDS050, and SN65LVDS051 RECEIVER

INPUTS	OUTPUT	
$V_{ID} = V_A - V_B$	RE	R
$V_{ID} \ge 50 \text{ mV}$	L	Н
$-50 \text{ mV} < V_{\text{ID}} < 50 \text{ mV}$	L	?
$V_{ID} \le -50 \text{ mV}$	L	L
Open	L	Н
X	Н	Z

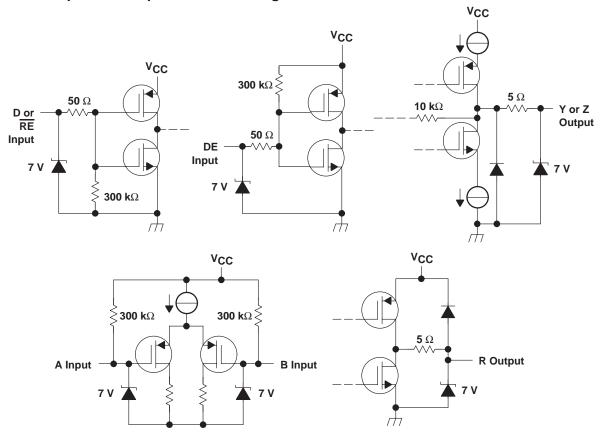
H = high level, L = low level, Z = high impedance, X = don't care

SN65LVDS180, SN65LVDS050, and SN65LVDS051 DRIVER

INPUTS		OUTPUTS		
D	DE	Υ	Z	
L	Н	L	Н	
Н	Н	Н	L	
Open	Н	L	Н	
Х	L	OFF	OFF	

H = high level, L = low level, OFF = No Output, X = don't care

equivalent input and output schematic diagrams



absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage range, V _{CC} (see Note 1)	0.5 V to 4 V
Voltage range: D, R, DE, RE	–0.5 V to 6 V
Y, Z, A, and B	–0.5 V to 4 V
Electrostatic discharge: Y, Z, A, B, and GND (see Note 2)	CLass 3, A:12 kV, B:600 V
All	Class 3, A:7 kV, B:500 V
Continuous power dissipation	See Dissipation Rating Table
Storage temperature range	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	250°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential I/O bus voltages are with respect to network ground terminal.

2. Tested in accordance with MIL-STD-883C Method 3015.7.

SN65LVDS179-Q1, SN65LVDS180-Q1, SN65LVDS050-Q1, SN65LVDS051-Q1 HIGH-SPEED DIFFERENTIAL LINE DRIVERS AND RECEIVERS

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DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{\scriptsize A}} \leq 25^{\circ}\mbox{\scriptsize C}$ POWER RATING	DERATING FACTOR ABOVE T _A = 25°C [†]	T _A = 85°C POWER RATING
PW(14)	736 mW	5.9 mW/°C	383 mW
PW(16)	839 mW	6.7 mW/°C	437 mW
D(8)	635 mW	5.1 mW/°C	330 mW/°C
D(14)	987 mW	7.9 mW/°C	513 mW/°C
D(16)	1110 mW	8.9 mW/°C	577 mW/°C

[†]This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

recommended operating conditions

	МІМ	NOM	MAX	UNIT
Supply voltage, V _{CC}	;	3.3	3.6	V
High-level input voltage, V _{IH}		2		V
Low-level input voltage, V _{IL}			0.8	V
Magnitude of differential input voltage, V _{ID}	0.	1	0.6	V
Magnitude of differential output voltage with disabled driver, V _{OD(dis)}			520	mV
Driver output voltage, VOY or VOZ)	2.4	V
Common-mode input voltage, V _{IC} (see Figure 5)	$\frac{\left V_{ D }\right }{2}$		$2.4 - \frac{\left V_{\mbox{\scriptsize ID}}\right }{2}$	V
Operating two pir temperature T.	4	`	VCC-0.8	°C
Operating free-air temperature, T _A	-4)	85	٠

device electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		METER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
		SN65LVDS179	No receiver load, driver $R_L = 100 \Omega$		9	12	mA
			Driver and receiver enabled, no receiver load, driver R _L = 100 Ω		9	12	
		010511/00400	Driver enabled, receiver disabled, $R_L = 100 \Omega$		5	7	mA
			Driver disabled, receiver enabled, no load		1.5	2	
			Disabled		0.5	1	
Icc			Drivers and receivers enabled, no receiver loads, driver R _L = 100 Ω		12	20	
	ourront		Drivers enabled, receivers disabled, R _L = 100 Ω		10	16	
				3	6	mA	
				0.5	1		
		SN65LVDS051	Drivers enabled, no receiver loads, driver $R_L = 100 \Omega$		12	20	A
		31403E4D3031	Drivers disabled, no loads		3	6	mA

[†] All typical values are at 25°C and with a 3.3-V supply.



SN65LVDS179-Q1, SN65LVDS180-Q1, SN65LVDS050-Q1, SN65LVDS051-Q1 HIGH-SPEED DIFFERENTIAL LINE DRIVERS AND RECEIVERS

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driver electrical characteristics over recommended operating conditions (unless otherwise noted)

	PARAMI	ETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{OD}	Differential output voltage r	nagnitude	B 400.0	247	340	454	
Δ V _{OD}	Change in differential outpu states	ut voltage magnitude between logic	$R_L = 100 \Omega$, See Figures 1 and 2	-50		50	mV
Voc(ss)	Steady-state common-mode	output voltage		1.125	1.2	1.375	V
ΔVOC(SS)	Change in steady-state com logic states	mon-mode output voltage between	See Figure 3	-50		50	mV
VOC(PP)	Peak-to-peak common-mode	e output voltage			50	150	mV
1	High level inner a compact	DE	V _{IH} = 5 V		-0.5	-20	^
lН	High-level input current	D			2	20	μА
	Laurence Construence	DE	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \		-0.5	-10	μΑ
اال	Low-level input current	D	V _{IL} = 0.8 V		2	10	
	01		VOY or $VOZ = 0$ V		3	10	
los	Short-circuit output current		V _{OD} = 0 V		3	10	mA
			DE = 0 V, V _{OY} = V _{OZ} = 0 V				
IO(OFF)	Off-state output current		$DE = V_{CC},$ $V_{OY} = V_{OZ} = 0 \text{ V},$ $V_{CC} < 1.5 \text{ V}$	-1		1	μΑ
C _{IN}	Input capacitance				3		pF

receiver electrical characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V _{IT+}	Positive-going differential input voltage threshold	Occ Firms Food Table 4			50	>/
VIT-	Negative-going differential input voltage threshold	See Figure 5 and Table 1	-50			mV
,,	Pale level extent calle as	$I_{OH} = -8 \text{ mA}$	2.4			.,
VOH	High-level output voltage	$I_{OH} = -4 \text{ mA}$	2.8			V
VOL	Low-level output voltage	I _{OL} = 8 mA			0.4	V
	Least surrect (A or B invote)	V _I = 0	-2	-11	-20	
1	Input current (A or B inputs)	V _I = 2.4 V	-1.2	-3		μΑ
I _I (OFF)	Power-off input current (A or B inputs)	$V_{CC} = 0$			±20	μΑ
lн	High-level input current (enables)	V _{IH} = 5 V			±10	μΑ
I _I L	Low-level input current (enables)	V _{IL} = 0.8 V			±10	μΑ
loz	High-impedance output current	V _O = 0 or 5 V			±10	μΑ
Cl	Input capacitance			5		pF

[†] All typical values are at 25°C and with a 3.3-V supply.

SN65LVDS179-Q1, SN65LVDS180-Q1, SN65LVDS050-Q1, SN65LVDS051-Q1 HIGH-SPEED DIFFERENTIAL LINE DRIVERS AND RECEIVERS

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driver switching characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
tPLH	Propagation delay time, low-to-high-level output			1.7	2.7	ns
tPHL	Propagation delay time, high-to-low-level output			1.7	2.7	ns
t _r	Differential output signal rise time	$R_L = 100 \Omega$		0.8	1	ns
t _f	Differential output signal fall time	C _L = 10 pF, See Figure 2		0.8	1	ns
tsk(p)	Pulse skew (t _{pHL} - t _{pLH}) [‡]			300		ps
tsk(o)	Channel-to-channel output skew§			150		ps
t _{en}	Enable time	0 5: 4		4.3	10	ns
t _{dis}	Disable time	See Figure 4		3.1	10	ns

[†] All typical values are at 25°C and with a 3.3-V.

receiver switching characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
tPLH	Propagation delay time, low-to-high-level output			3.7	4.5	ns
tPHL	Propagation delay time, high-to-low-level output			3.7	4.5	ns
tsk(p)	Pulse skew (t _{pHL} - t _{pLH}) [‡]	C _L = 10 pF, See Figure 6		0.3		ns
t _r	Output signal rise time			0.7	1.5	ns
t _f	Output signal fall time			0.9	1.5	ns
^t PZH	Propagation delay time, high-level-to-high-impedance output			2.5		ns
t _{PZL}	Propagation delay time, low-level-to-low-impedance output	7		2.5		ns
tPHZ	Propagation delay time, high-impedance-to-high-level output	See Figure 7		7		ns
t _{PLZ}	Propagation delay time, low-impedance-to-high-level output			4		ns

[†] All typical values are at 25°C and with a 3.3-V.



[‡]t_{sk(p)} is the magnitude of the time difference between the high-to-low and low-to-high propagation delay times at an output.

[§] $t_{sk(0)}$ is the magnitude of the time difference between the outputs of a single device with all of their inputs connected together.

t_{Sk(pp)} is the magnitude of the time difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, same temperature, and have identical packages and test circuits.

 $[\]ddagger$ $t_{sk(p)}$ is the magnitude of the time difference between the high-to-low and low-to-high propagation delay times at an output. \ddagger $t_{sk(p)}$ is the magnitude of the time difference between the outputs of a single device with all of their inputs connected together.

¹ t_{sk(pp)} is the magnitude of the time difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, same temperature, and have identical packages and test circuits.

PARAMETER MEASUREMENT INFORMATION

driver

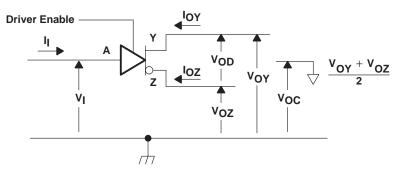
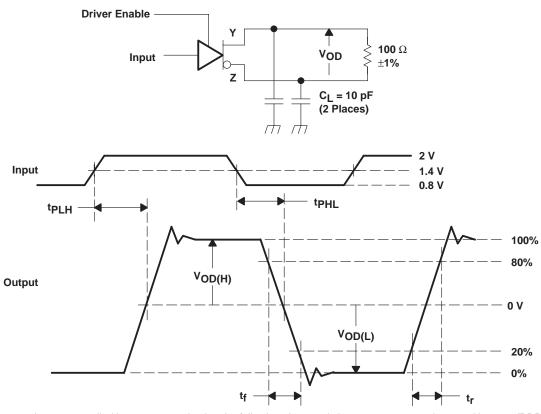


Figure 1. Driver Voltage and Current Definitions



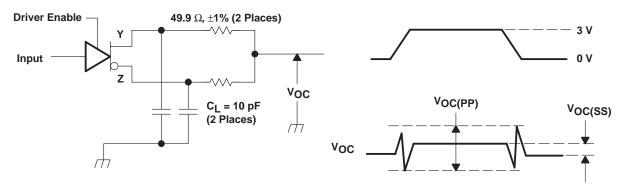
NOTE A: All input pulses are supplied by a generator having the following characteristics: t_{Γ} or $t_{\Gamma} \le 1$ ns, pulse repetition rate (PRR) = 50 Mpps, pulse width = 10 ± 0.2 ns. C_L includes instrumentation and fixture capacitance within 0,06 mm of the D.U.T.

Figure 2. Test Circuit, Timing, and Voltage Definitions for the Differential Output Signal



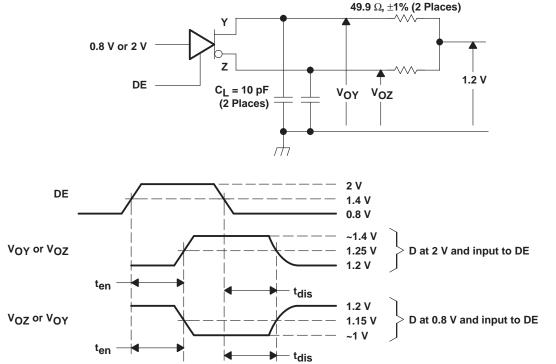
PARAMETER MEASUREMENT INFORMATION

driver (continued)



NOTE A: All input pulses are supplied by a generator having the following characteristics: t_f or $t_f \le 1$ ns, pulse repetition rate (PRR) = 50 Mpps, pulse width = 10 ± 0.2 ns. C_L includes instrumentation and fixture capacitance within 0,06 mm of the D.U.T. The measurement of $V_{OC(PP)}$ is made on test equipment with a -3 dB bandwidth of at least 300 MHz.

Figure 3. Test Circuit and Definitions for the Driver Common-Mode Output Voltage



NOTE A: All input pulses are supplied by a generator having the following characteristics: t_f or $t_f \le 1$ ns, pulse repetition rate (PRR) = 0.5 Mpps, pulse width = 500 ± 10 ns. C_1 includes instrumentation and fixture capacitance within 0,06 mm of the D.U.T.

Figure 4. Enable and Disable Time Circuit and Definitions



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PARAMETER MEASUREMENT INFORMATION

receiver

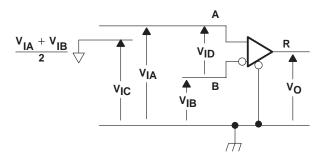


Figure 5. Receiver Voltage Definitions

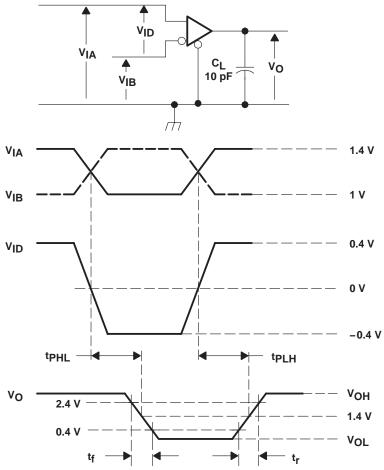
Table 1. Receiver Minimum and Maximum Input Threshold Test Voltages

	VOLTAGES V)	RESULTING DIFFERENTIAL INPUT VOLTAGE (mV)	RESULTING COMMON- MODE INPUT VOLTAGE (V)		
VIA	V _{IB}	V _{ID}	V _{IC}		
1.25	1.15	100	1.2		
1.15	1.25	-100	1.2		
2.4	2.3	100	2.35		
2.3	2.4	-100	2.35		
0.1	0	100	0.05		
0	0.1	-100	0.05		
1.5	0.9	600	1.2		
0.9	1.5	-600	1.2		
2.4	1.8	600	2.1		
1.8	2.4	-600	2.1		
0.6	0	600	0.3		
0	0.6	-600	0.3		

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PARAMETER MEASUREMENT INFORMATION

receiver (continued)

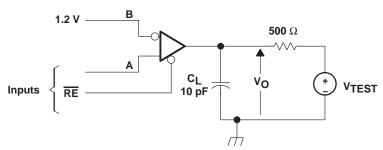


NOTE A: All input pulses are supplied by a generator having the following characteristics: t_f or $t_f \le 1$ ns, pulse repetition rate (PRR) = 50 Mpps, pulse width = 10 ± 0.2 ns. C_L includes instrumentation and fixture capacitance within 0,06 m of the D.U.T.

Figure 6. Timing Test Circuit and Waveforms

PARAMETER MEASUREMENT INFORMATION

receiver (continued)



NOTE A: All input pulses are supplied by a generator having the following characteristics: t_f or $t_f \le 1$ ns, pulse repetition rate (PRR) = 0.5 Mpps, pulse width = 500 ± 10 ns. C_L includes instrumentation and fixture capacitance within 0,06 m of the D.U.T.

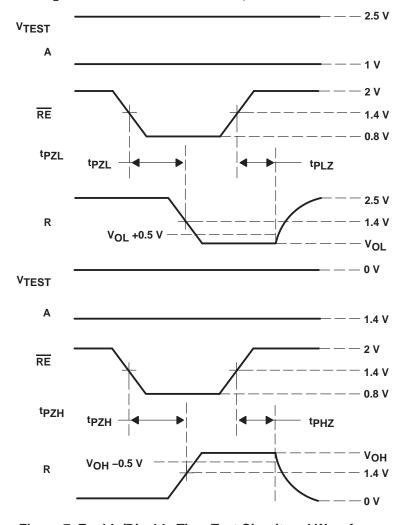
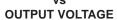


Figure 7. Enable/Disable Time Test Circuit and Waveforms

TYPICAL CHARACTERISTICS

DISABLED DRIVER OUTPUT CURRENT



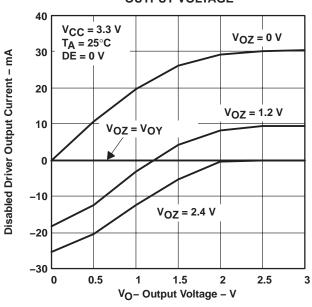


Figure 8

DRIVER LOW-LEVEL OUTPUT VOLTAGE

LOW-LEVEL OUTPUT CURRENT

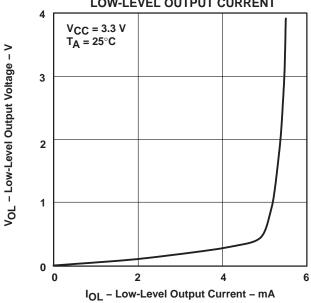


Figure 9

DRIVER HIGH-LEVEL OUTPUT VOLTAGE

HIGH-LEVEL OUTPUT CURRENT

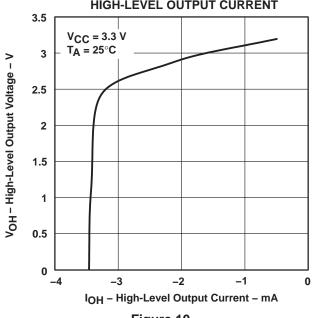
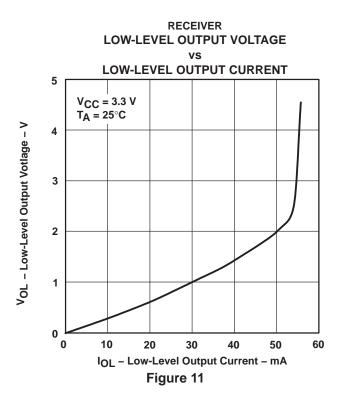
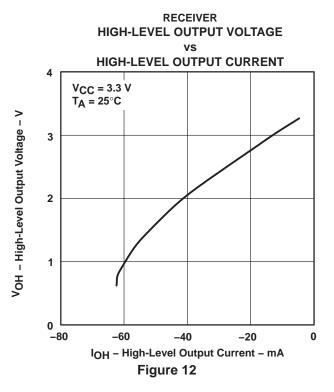


Figure 10

TYPICAL CHARACTERISTICS

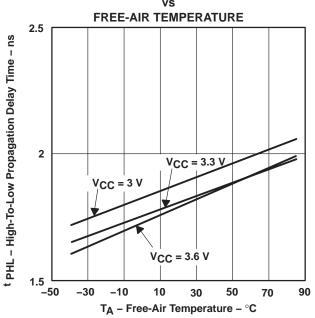




DRIVER

LOW-TO-HIGH LEVEL PROPAGATION DELAY TIME

DRIVER
HIGH-TO-LOW LEVEL PROPAGATION DELAY TIME



vs FREE-AIR TEMPERATURE 2.5 ^t PLH - Low-To-High Propagation Delay Time - ns 2 V_{CC} = 3.3 V $V_{CC} = 3 V$ V_{CC} = 3.6 V 1.5 -50 -30 10 -10 30 50 90

Figure 13

Figure 14

 T_A – Free-Air Temperature – $^{\circ}C$

TYPICAL CHARACTERISTICS

RECEIVER HIGH-TO-LOW LEVEL PROPAGATION DELAY TIME

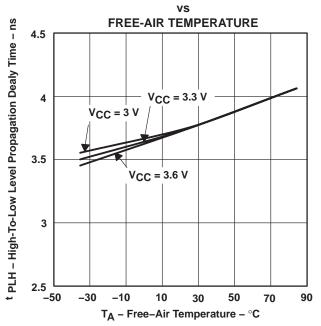


Figure 15

RECEIVER LOW-TO-HIGH LEVEL PROPAGATION DELAY TIME

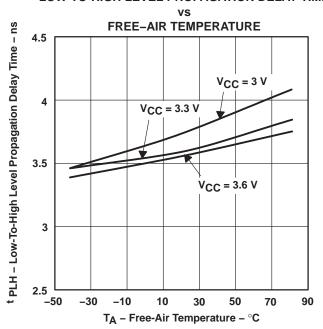


Figure 16

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APPLICATION INFORMATION

The devices are generally used as building blocks for high-speed point-to-point data transmission. Ground differences are less than 1 V with a low common–mode output and balanced interface for very low noise emissions. Devices can interoperate with RS-422, PECL, and IEEE-P1596. Drivers/receivers maintain ECL speeds without the power and dual supply requirements.

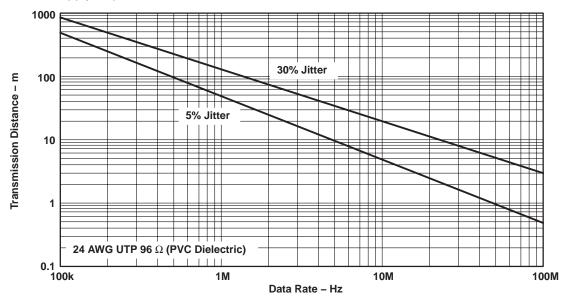


Figure 17. Data Transmission Distance Versus Rate



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APPLICATION INFORMATION

fail safe

One of the most common problems with differential signaling applications is how the system responds when no differential voltage is present on the signal pair. The LVDS receiver is like most differential line receivers, in that its output logic state can be indeterminate when the differential input voltage is between –100 mV and 100 mV and within its recommended input common-mode voltage range. TI's LVDS receiver is different in how it handles the open-input circuit situation, however.

Open-circuit means that there is little or no input current to the receiver from the data line itself. This could be when the driver is in a high-impedance state or the cable is disconnected. When this occurs, the LVDS receiver will pull each line of the signal pair to near V_{CC} through 300-k Ω resistors as shown in Figure 18. The fail-safe feature uses an AND gate with input voltage thresholds at about 2.3 V to detect this condition and force the output to a high-level regardless of the differential input voltage.

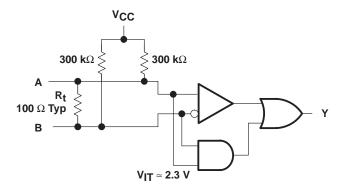


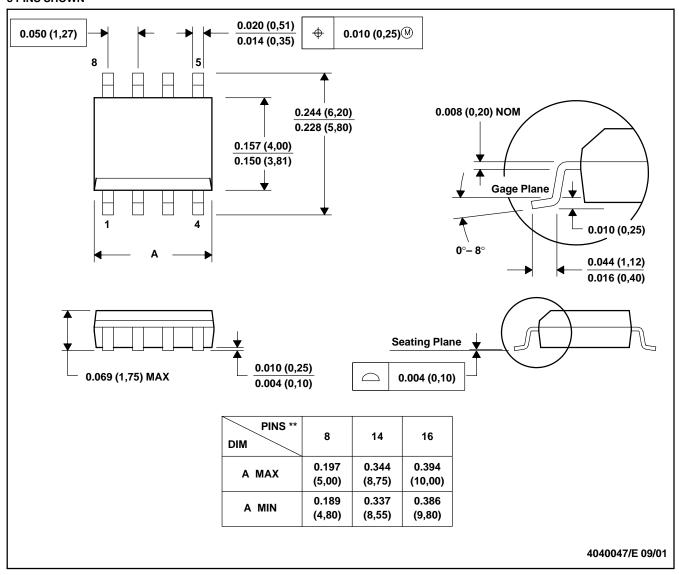
Figure 18. Open-Circuit Fail Safe of the LVDS Receiver

It is only under these conditions that the output of the receiver will be valid with less than a 100-mV differential input voltage magnitude. The presence of the termination resistor, Rt, does not affect the fail-safe function as long as it is connected as shown in the figure. Other termination circuits may allow a dc current to ground that could defeat the pullup currents from the receiver and the fail-safe feature.

D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

8 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

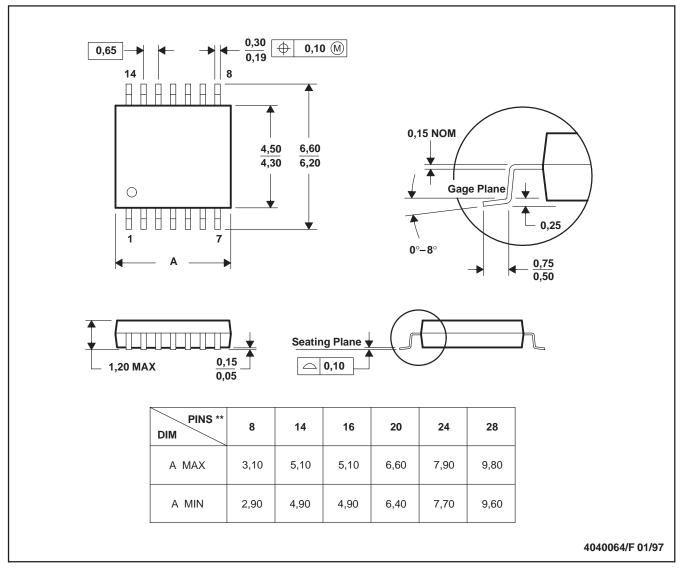
C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153





ti.com 25-Feb-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN65LVDS051DRQ1	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN65LVDS051PWRQ1	ACTIVE	TSSOP	PW	16	2000	None	CU NIPDAU	Level-1-220C-UNLIM
SN65LVDS180DRQ1	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN65LVDS180PWRQ1	ACTIVE	TSSOP	PW	14	2000	None	CU NIPDAU	Level-1-250C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

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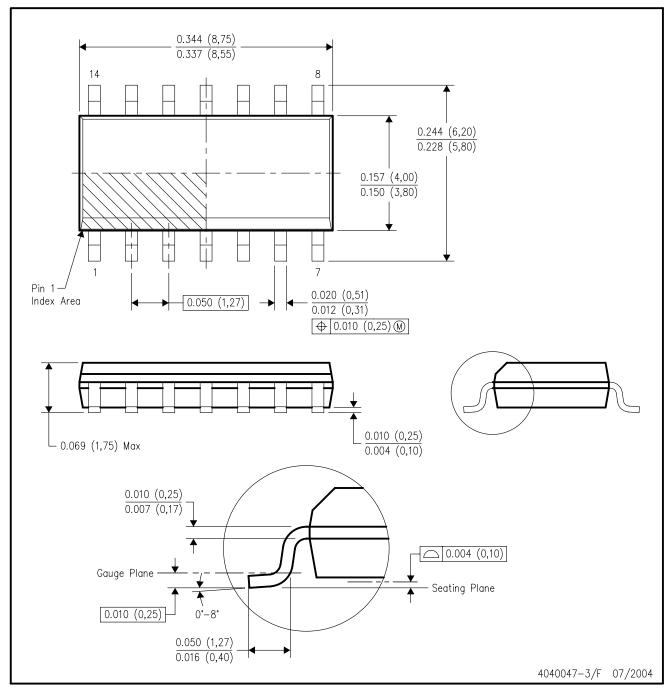
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



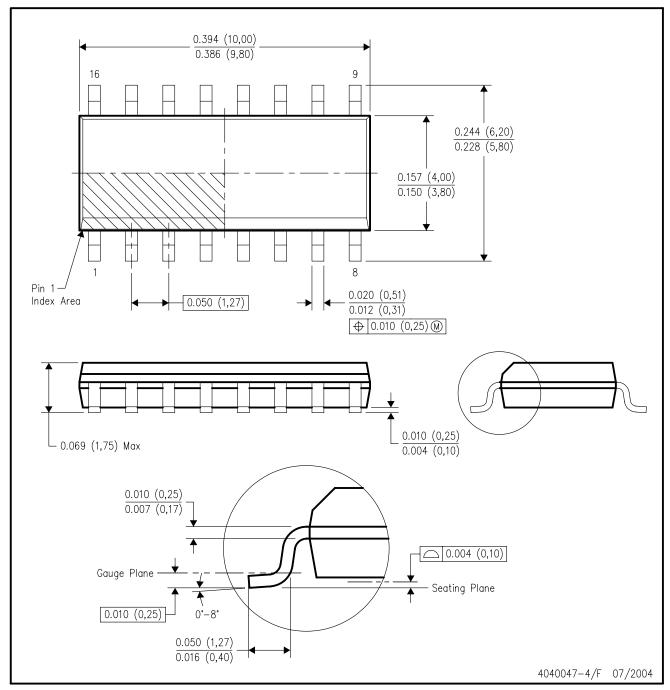
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

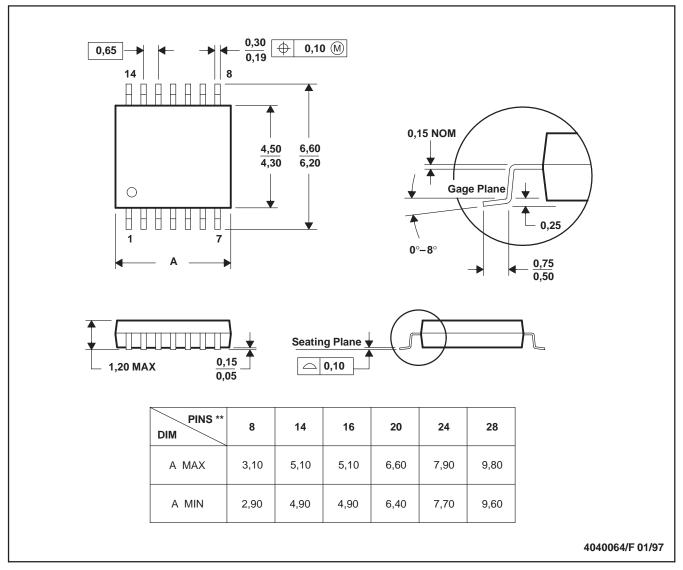
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.



PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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